

iG-G47V®

Virtex™ UltraScale+™ FPGA 3U VPX Plug-in Module (Payload Profile)

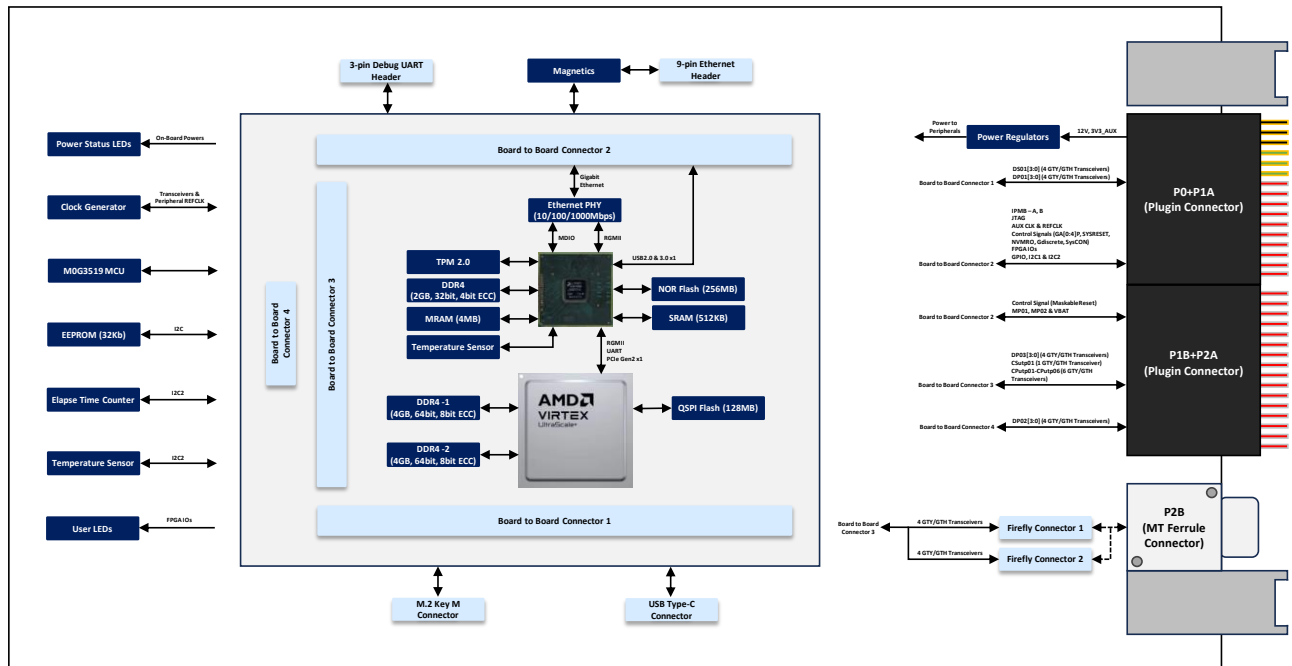
iWave's Virtex™ UltraScale+™ 3U VPX Plug-in Module comprises of Virtex™ UltraScale+™ FPGA SOM and 3U VPX Carrier Board. Virtex™ UltraScale+™ FPGA SOM is compatible with VU13P, VU11P, VU09P, VU07P, VU05P, VU190, VU160, VU125, VU095 & VU080 Devices. It has 3780K FPGA Logic Cells, 1780K LUTs and Dual-core Arm® Cortex®-A7 @up to 1.2GHz. It is equipped with 3U VPX Connectors (P0, P1A+P1B & P2A) based on VITA 46.0 and MT Ferrule Connector (P2B) based on VITA 67.3. It has Dual 64-bit, 4GB FPGA DDR4 with 8-bit ECC & 128MB QSPI Flash for FPGA and 2GB DDR4 with 4-bit ECC, 256MB NOR Flash, 4MB MRAM & 512KB SRAM for CPU.



Highlights

- ❖ SOSA aligned Virtex™ UltraScale+™ FPGA 3U VPX Plug-in Module
- ❖ Compatible with VU13P, VU11P, VU09P, VU07P, VU05P, VU190, VU160, VU125, VU095 & VU080 Devices
- ❖ Dual 64-bit, 4GB FPGA DDR4 & Single 32-bit, 2GB CPU DDR4
- ❖ Supports SOSA Aligned Payload Profiles
- ❖ IPMC with Arm® 32-bit Cortex®-M0+ CPU @up to 80MHz
- ❖ LS1021A with Dual-core Arm® Cortex®-A7 @up to 1.2GHz
- ❖ 10+ years Long Support

Block Diagram



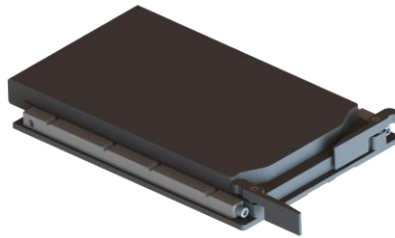
Profile Specifications:

- Slot Profile: SLT3-PAY-1F1U1S1S1U1U4F1J-14.6.13-0 (Without Fibre ports)
Module Profile as per AMPS: MODA3-16.6.13-1-0-F2C-[E8-E7][P3D-P3D][E7][N]
- Slot Profile: SLT3-PAY-1F1U1S1S1U1U4F1J-14.6.13-4 (With 12 Fibre ports)
Module Profile as per AMPS: MODA3-16.6.13-1-4-F2C-[E8-E7][P3D-P3D][E7][E12]

Technical Specifications

SoC/FPGA	Virtex™ UltraScale+™ FPGA with B2104 Package Compatible with VU13P, VU11P, VU09P, VU07P, VU05P, VU190, VU160, VU125, VU095 & VU080 Devices Up to 1842.75K FPGA Logic Cells & 842.4K LUTs	3U VPX Backplane: Connector - P1A+P1B	Data Plane Port-01
CPU	LS1021A with Dual-core Arm® Cortex®-A7 @up to 1.2GHz		• DP01[3:0] - Up to 40G Ethernet Data Plane Port
Memory & Storage	FPGA - Dual 64-bit, 4GB DDR4 with 8-bit ECC (Upgradable up to 8GB) 128MB QSPI Flash CPU - Single 32-bit, 2GB DDR4 with 4-bit ECC 256MB NOR Flash 4MB MRAM & 512KB SRAM		• DPutp01 - Up to 10G Ethernet Control Plane Port
			• CPutp01 - Up to 10G Ethernet Expansion Plane
IPMC	IPMC with Arm® 32-bit Cortex®-M0+ CPU @up to 80MHz Up to 512KB of Flash Memory & 128KB of Total SRAM	3U VPX Backplane: Connector – P2A	• EP[0:7] – PCIe Gen3 x8 Control Signals (MaskableReset, Gdiscrete,SysCON) MP01, MP02 & VBAT
SoC/FPGA to CPU Interfaces	PCIe Gen2 x1 RGMII UART	3U VPX Backplane: Connector – P2B	Expansion Plane
VPX Front Panel Features	USB3.0 & USB 2.0 through USB Type-C Connector x1 10/100/1000Mbps Ethernet through 9-Pin Header x1 3-Pin Console UART Header x1	VPX On-Board Features	• EP[8:15] – PCIe Gen3 x8 MT Ferrule Optical Interconnect with Aperture Pattern J Supports MM12F - 12 Fibre ports
3U VPX Backplane: Connector - P0	Utility Plane - IPMB - A, B - JTAG - System Reference Clocks (REF_CLK, AUX_CLK) - Power Input (12V VDC, 3.3V_AUX) - Control Signals (GA[0:4]P,SYSRESET,NVMRO)	Profile Specification	32Kb EEPROM x1 PCIe Gen2 x1 through M.2 (Key-M) Connector x1 Temperature Sensor x1 Elapse Time Counter x1 On-Board Clock Generators
		General Specification	• Slot Profile: SLT3-PAY-1F1U1S1S1U1U4F1J-14.6.13-0 (Without Fibre ports) Module Profile as per AMPS: MODA3-16.6.13-1-0-F2C-(E8-E7)(P3D-P3D)(E7)[N] • Slot Profile: SLT3-PAY-1F1U1S1S1U1U4F1J-14.6.13-4 (With 12 Fibre ports) Module Profile as per AMPS: MODA3-16.6.13-1-4-F2C-(E8-E7)(P3D-P3D)(E7)[E12]
			• Slot Pitch: 1 Inch Conduction Cooled • BSP Support: Linux/Vivado 2024 or above • Environmental Specification: RoHS & REACH Compliant

Product Accessories



Thermal Solutions

For any highly integrated FPGA VPX Plug-in Module, thermal design is a very important factor. iWave supports a VITA 65.0 compliant 3U Conduction Cooled Heat Spreader

Applications

▪ Military & Aerospace Systems

Designed for Military & Aerospace systems, It delivers high-performance processing, secure computing, and rugged reliability for mission-critical applications.

▪ Embedded Computing

Optimized for embedded computing, It delivers high-performance processing, low-latency data handling, and scalable integration for advanced embedded systems..

▪ Data Center & Network Infrastructure

Ideal for Data Center & Network Infrastructure, it enables high-speed data processing, low-latency networking, and scalable acceleration for next-generation communication systems.

▪ Sensor Networks and Telecommunications

Optimized for Sensor Networks and Telecommunications, it delivers high-speed signal processing, real-time data analytics, and reliable connectivity for advanced communication systems.

A Global Leader in Embedded Systems Engineering and Solutions

Since 1999, we have pioneered leadership in embedded systems technology, establishing ourselves as a strategic embedded technology partner for advanced solutions. Our comprehensive portfolio encompasses ARM and FPGA System on Modules, COTS FPGA solutions, and ODM solutions which include Telematics, Gateways & HMI Solutions.

Beyond our robust product ecosystem, we provide comprehensive ODM support with specialized custom design and manufacturing capabilities, enabling customers to accelerate and optimize their product development roadmaps. With a strategic focus on industrial, automotive, medical, and avionics markets, we deliver innovative technology solutions to global clients.

mktg@iwave-global.com

iWave Global
Bangalore, India

iWave Global
Ras Al Khaimah, UAE.

iWave Global GmbH
Ratingen, Germany.

iWave Europe
Rotterdam, Netherlands.

iWave USA
California, USA.

iWave Global East Coast LLC
New Jersey, USA.

iWave APAC
Taipei City, Taiwan.

iWave Korea
Gyeonggi,-do, Korea.

iWave Japan
Yokohama, Kanagawa.

Sakura Global
Kagoshima, Japan.

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